

●Recommended soldering conditions (Lead frame type)

1. Not to apply high temperature exceeding the maximum storage temperature to the epoxy resin.
2. Not to apply any force to the epoxy resin at high temperature.
3. Soldering process
 - (1) The distance between holes should be the same as that of between terminal leads of the component to avoid any stress during the soldering process. The stress may lead to the open circuit. Also, lead forming should be done before soldering process not to apply any stress to the inside of the epoxy resin.
 - (2) Not to apply any stress to the component during the soldering process.
 - (3) Recommended soldering condition.

	(Condition)
Pre-heating & solder bath	Pre-heating : Less than 90°C Solder bath : Less than 265°C Soldering area : 3mm away from the bottom of the epoxy resin. Dip time : Less than 5 seconds. Less than twice.
Soldering iron	Temperature : Less than 400°C ±10°C. within 3 seconds, 2times Soldering area : 3mm away from the bottom of the epoxy resin.

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